AMENDMENTS TO THE CLAIMS

Please amend the Claims as reflected in the following complete listing of Claims:

- 1. (withdrawn) A photovoltaic device comprising:
 - (a) a substrate comprising silicon doped with a first dopant, the substrate having a front surface, a substantially smooth back surface, and at least one edge surface;
 - (b) a first layer comprising a second dopant of a conductivity type opposite to the first dopant at the front surface and at the at least one edge surface; and
 - (c) a surface coating disposed over the front surface.
- 2. (withdrawn) The photovoltaic device of Claim 1 wherein the surface coating is disposed over the at least one edge surface.
- 3. (withdrawn) The photovoltaic device of Claim 2 wherein the surface coating is disposed over the periphery of the back surface.
- 4. (withdrawn) The photovoltaic device of Claim 1 wherein the front surface is textured.
- 5. (withdrawn) The photovoltaic device of Claim 1 wherein the back surface is free or substantially free of the second dopant.
- 6. (withdrawn) The photovoltaic device of Claim 5 further comprising a back surface field.
- 7. (withdrawn) The photovoltaic device of Claim 6 wherein the back surface field is formed by a second layer at at least a portion of the back surface, the second layer comprising aluminum alloyed with the substrate.
- 8. (withdrawn) The photovoltaic device of Claim 1 wherein the surface coating comprises silicon nitride.

- A photovoltaic module comprising the photovoltaic device of 9. (withdrawn) Claim 1.
- A photovoltaic device comprising: . 10. (withdrawn)
 - a substrate comprising doped silicon, the substrate having a back (a) surface substantially free of a p-n junction and having a p-n junction proximal to a front surface and a p-n junction proximal to at least one edge surface; and
 - a surface coating disposed over the front surface. (b)
- The photovoltaic device of Claim 10 wherein the surface 11. (withdrawn) coating is disposed over the at least one edge surface.
- 12. (withdrawn) The photovoltaic device of Claim 11 wherein the surface coating is disposed over the periphery of the back surface.
- The photovoltaic device of Claim 10 wherein the front 13. (withdrawn) surface is textured.
- The photovoltaic device of Claim 13 wherein the back 14. (withdrawn) surface is substantially smooth.
- The photovoltaic device of Claim 14 further comprising a 15. (withdrawn) back surface field.
- The photovoltaic device of Claim 10 wherein the surface 16. (withdrawn) coating comprises silicon nitride.
- A process for making a photovoltaic device using a 17. (currently amended) substrate comprising silicon doped with a first dopant, the process comprising the steps of:
 - forming a first layer of the substrate at a front surface and at least (a) one edge surface, the first layer comprising a second dopant of a conductivity type opposite the first dopant;

- (b) disposing over the first layer a surface coating such that a back surface of the substrate is free or substantially free of the surface coating; and
- (c) removing the second dopant from the back surface such that the back surface is free or substantially free of the second dopant.
- 18. (original) The process according to Claim 17 further comprising the step of texturing the substrate.
- 19. (original) The process according to Claim 18 further comprising the step of removing the texture from the back surface such that the back surface is substantially smooth.
- 20. (original) The process according to Claim 19 further comprising the step of forming a back surface field.
- 21. (original) The process according to Claim 17 wherein the surface coating comprises silicon nitride.
- 22. (withdrawn) A process for making a photovoltaic device using a substrate comprising doped silicon, the process comprising the steps of:
 - (a) forming a p-n junction proximal to the entire surface of the substrate:
 - (b) forming a surface coating disposed over the substrate such that a back surface remains free or substantially free of the surface coating; and
 - (c) removing the p-n junction from the back surface such that the back surface is free or substantially free of the p-n junction.
- 23. (withdrawn) The process according to Claim 22 wherein the surface coating comprises silicon nitride.
- 24. (withdrawn) The process according to Claim 22 further comprising the step of texturing the substrate.

- The process according to Claim 24 further comprising the 25. (withdrawn) step of removing the texture from the back surface such that the back surface is substantially smooth.
- The process according to Claim 25 further comprising the 26. (withdrawn) step of forming a back surface field.
- A process for making a photovoltaic device using a substrate 27. (withdrawn) comprising silicon doped with a first dopant, the process comprising the steps of:
 - forming a first layer on at least a front surface of the substrate, the first layer comprising a second dopant of a conductivity type opposite the first dopant;
 - forming a surface coating disposed over the substrate such that a back surface of the substrate is free or substantially free of the surface coating; and
 - (c) etching the back surface of the substrate.
- 28. (previously presented) The process of Claim 17 wherein the surface coating is formed such that only a back surface of the substrate is free or substantially free of the surface coating.
- The process of Claim 28 wherein the first layer is formed at 29. (withdrawn) all surfaces of the substrate.
- 30. (withdrawn) The process of Claim 29 wherein a second layer comprising an oxide of the substrate is formed over the first layer and is removed prior to the step of forming a surface coating.
- 31. (previously presented) The process of Claim 17 wherein, in the step of disposing over the first layer a surface coating such that a back surface of the substrate is free or substantially free of the surface coating, the surface coating is also formed on the periphery of the back surface.